



DISCRIPTION

FEATURES

Ceramic Core High frequency design Excellent Q values Excellent SRF High reliability Excellent thermal stability

OPTIONS

Tape & Reel is Standard (Qty: 3.000 Pcs) Bulk Packing Available for smaller quantites Tolerance: J = 5% and K=10% is Standard, tighter Tolerance available (MOQ on request)

APPLICATIONS

Modems Mobile Radios Cordless Telephones Global Positioning Systems Telecommunications Systems

PHYSICAL CHARACTERISTICS

- Testing : (Equivalents acceptable) Inductance & Q-HP4191A + HP4291A SRF : HP8553B ; RDC : 25°C
- Operating Temperature : Ceramic -55°C ~ 125°C
- Pad metalization : Tungsten-nickel with gold flash
- Solder methods : Wave, Reflow, Vapor Phase
- Solderability : Max 260°C for 10 seconds
- Marking : EIA color code

ELECTRICAL SPECIFICATIONS

Properties	Test conditions		Value	Unit	Tol.
Inductance		L	150	nH	see Site 2
Q factor		Q	45		min.
DC-resistance		DCR typ.		Ω	typ.
DC-resistance		DCR max.	0,700	Ω	max.
Self-Res. Freq.		SRF	850	Mhz	min.
Test-Freq.			100	Mhz	
Rated Current		IDC	580	mA	max.
Saturation Current		Isat		mA	typ.

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	must be informed ach electronic com					Part No.:	S12	2004-R15
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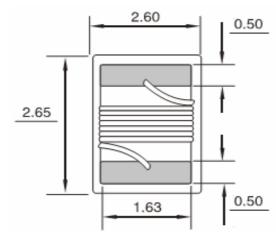
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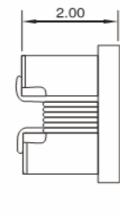


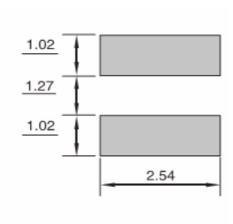


TECHNICAL INFORMATIONS

Dimensions (mm)



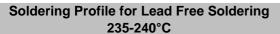


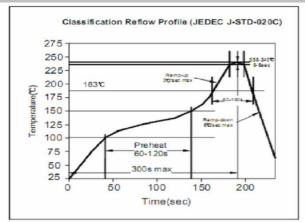


Ordering Information

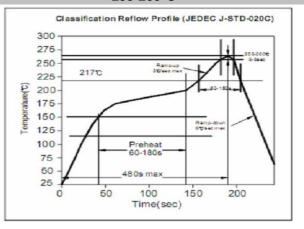
Serie and Range S12004-R15

Tolerance	ROHS	Packing			
ĸ	D	TR			
n	R	IR			
J = 5%	R = ROHS	BU = Bulk Ware			
K = 10%	N = non ROHS	TR = Tape Reel			
M = 20%					
N = 30%					





Soldering Profile for Lead Free Soldering 255-260°C



 This electronic component is meant to be used in general electronic equipment. Before the incorporation of this component into any equipment with higher and more reliable requirements such as aviation, aerospace, submarine, nuclear control, transportation, transportation signal, disaster prevention, medical, public information network, etc. or if there is a possibility of injuries or damages to the human body, Edcon 						SMT WIRE-WOUND CERAMIC CHIP INDUCTORS		
-Components must be informed before the stage of design-in. Evaluation checks for safety have to be performed on each electronic components used in electrical circuits that require high safety and reliability					Part No.:	S12004-R15		
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